

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re applicati	on of: Rich Fogal and Michael B. Ball	§		
• •	•	§	Group Art Unit	: 2822
Serial No.:	09/422,887	§		
		§	Examiner:	J. Brophy
Filed:	October 21, 1999	§		
		§	Atty. Docket:	95-0134.05
For: ANGULARLY OFFSET STACKED DIE		§		
MULTICHIP DEVICE AND METHOD OF				
MANUFACTURE		§		
		2		

AMENDMENT AND RESPONSE AFTER THE BOARD DECISION DATED FEBRUARY 10, 2004

Certificate of Mailing (37 C.F.R.§ 1.8)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:

4/12/04

Signature

Applicants herein respond to the Board decision dated February 10, 2004. Please amend the above-captioned application as follows.